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Amend. B
Cheresa
4-4-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Mike F. Chang et al.
Assignee: Siliconix Incorporated
Title: Semiconductor Die Package Including Cup-Shaped Leadframe
Application No.: 09/468,249 Filing Date: December 10, 1999
Examiner: S. Rao Group Art Unit: 2814
Docket No.: M-7970 US

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San Jose, California
March 27, 2002

BOX RCE
COMMISSIONER FOR PATENTS
Washington, D.C. 20231

RESPONSE TO FINAL OFFICE ACTION WITH RCE

Dear Sir:

Applicants submit this amendment in response to the final rejection Office Action in the above application having a mailing date of December 4, 2001. A Petition for Extension of Time to respond is enclosed herewith, and a Request for Continued Examination.

IN THE SPECIFICATION

At page 4, first paragraph, please amend the specification as follows: Attached hereto is Appendix A showing the change to the specification; language that has been deleted is shown in brackets.

The package of this invention is economical to manufacture and provides electrical contacts to both sides of a dice. In addition, the direct connection between the die and the PCB provides a good thermal conduction path from the die to the PCB.

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LAW OFFICES OF
SKJERVEN MORRILL
MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979